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SG5851
Low-Cost Green-Mode PWM Controller for Flyback Converters

Features

- Green-Mode PWM
- Supports the "Blue Angel" Standard
- Low Start-up Current: 9μA
- Low Operating Current: 3mA
- Leading-Edge Blanking
- Constant Output Power Limit
- Universal Input
- Built-in Synchronized Slope Compensation
- Current Mode Operation
- Cycle-by-cycle Current Limiting
- Under-Voltage Lockout (UVLO)
- Programmable PWM Frequency with Frequency Hopping
- V_{DD} Over-Voltage Protection (Auto Restart)
- Gate Output Voltage Clamped at 17V
- Low Cost
- Few External Components Required

Applications

- Power Adaptors
- Open-Frame SMPS

Description

This highly integrated PWM controller provides several special enhancements designed to meet the low standby-power needs of low-power SMPS. To minimize standby power consumption, the proprietary green-mode function provides off-time modulation to linearly decrease the switching frequency under light-load conditions. This green-mode function enables the power supply to meet even the strictest power conservation requirements.

The BiCMOS fabrication process enables reducing the start-up current to 9μA and the operating current to 3mA. To further improve power conservation, a large start-up resistance can be used. Built-in synchronized slope compensation ensures the stability of peak current mode control. Proprietary internal compensation provides a constant output power limit over a universal AC input range (90V_{AC} to 264V_{AC}). Pulse-by-pulse current limiting ensures safe operation even during short-circuit conditions.

To protect the external power MOSFET from being damaged by supply over voltage, the output driver is clamped at 17V. SG5851 controllers, available in an SOP package, can be used to improve the performance and reduce the production cost of power supplies.

Ordering Information

Part Number	Operating Temperature Range	Package	Packing Method
SG5851SZ	-40°C to +85°C	8-pin Small Outline Package (SOP)	Tape & Reel
SG5851DZ	-40°C to +85°C	8-pin Dual in-line Package (DIP)	Rail

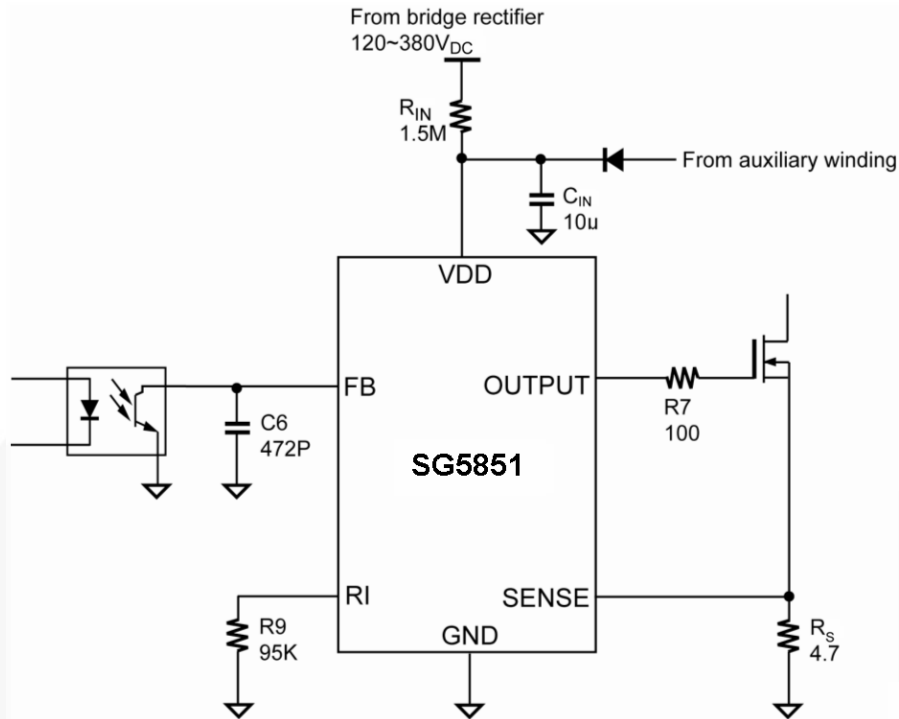All packages are lead free per JEDEC: J-STD-020B standard.

Application Diagram

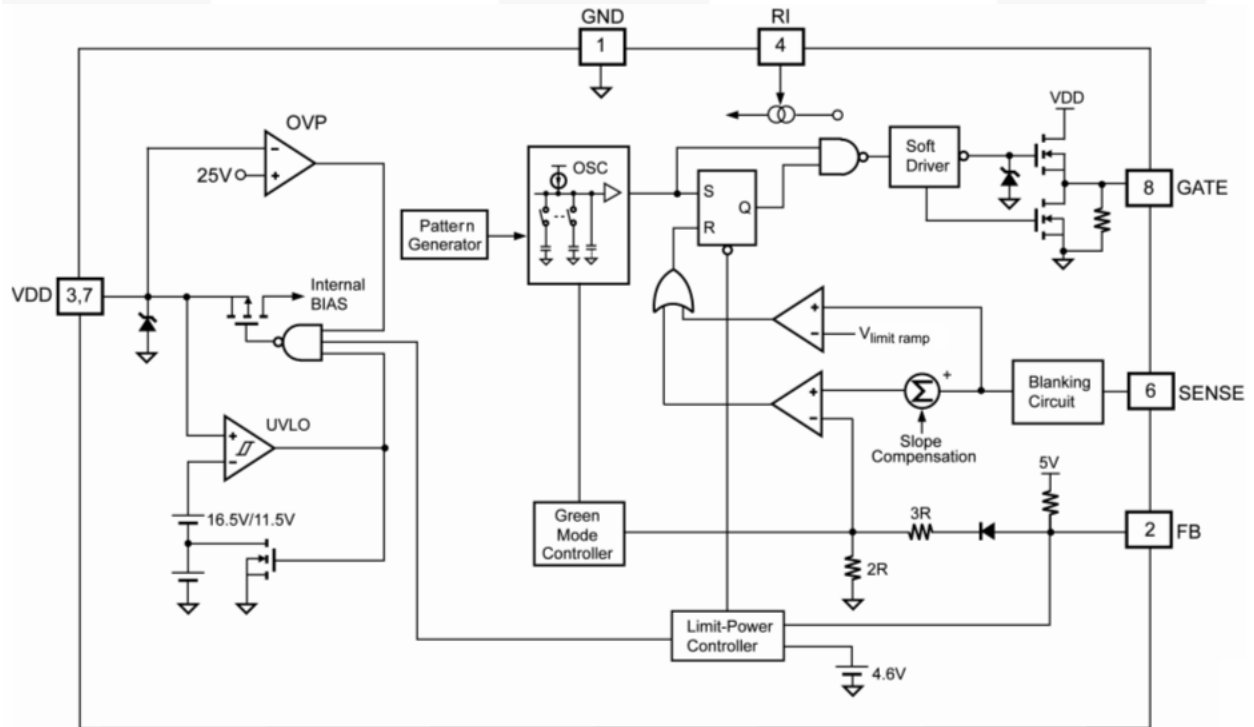**Figure 1.   Typical Application**

Block Diagram
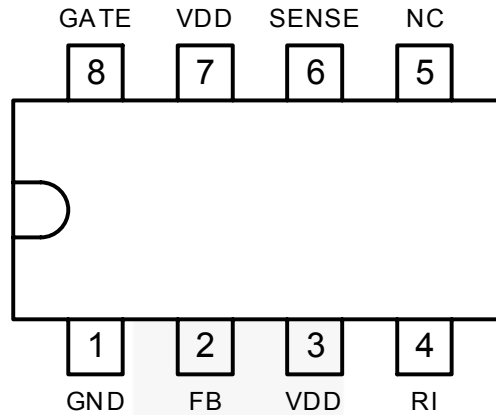

Figure 2.   Function Block Diagram

Pin Configuration

Figure 3. Pin Configuration(Top View)

Pin Definitions

Pin #	Name	Description
1	GND	**Ground**. For ATX SMPS, it detects AC line voltage through the main transformer.
2	FB	**Feedback**.
3	VDD	**Power Supply**.
4	RI	**Reference Setting**. A resistor connected from the RI pin to ground generates a constant current source used to charge an internal capacitor and determine the switching frequency. Increasing the resistance reduces the amplitude of the current source and reduces the switching frequency. A 95kΩ resistor, R_I, results in a 50μA constant current I_I and a 70kHz switching frequency.
5	NC	**No Connection**.
6	SENSE	**Current Sense**. This pin senses the voltage across a resistor. When the voltage reaches the internal threshold, PWM output is disabled. This activates over-current protection. This pin also provides current amplitude information for current-mode control.
7	VDD	**Power Supply**.
8	GATE	**Driver Output**. The totem-pole output driver for driving the power MOSFET.

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter	Min.	Max.	Unit
V_{VDD}	DC Supply Voltage		30	V
V_{FB}	Input Voltage to FB Pin	-0.5	7.0	V
V_{SENSE}	Input Voltage to Sense Pin	-0.5	7.0	V
P_D	Power Dissipation		300	mW
T_J	Operating Junction Temperature		150	°C
θ_{JA}	Thermal Resistance (Junction to Air)		141	°C/W
T_{STG}	Storage Temperature Range	-55	150	°C
T_L	Lead Temperature (Wave soldering, or IR 10 seconds)		260	°C
ESD	Electrostatic Discharge Capability, Human Body Model		3.0	KV
	Electrostatic Discharge Capability, Machine Model		200	V

Notes:
1. All voltage values, except differential voltage, are given with respect to GND pin.
2. Stresses beyond those listed under "absolute maximum ratings "may cause permanent damage to the device.

Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to Absolute Maximum Ratings.

Symbol	Parameter	Min.	Typ.	Max.	Unit
T_A	Operating Ambient Temperature	-40		+85	°C

Electrical Characteristics

V_{DD} =15V, T_A= 25°C, unless noted operating specs.

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Units
V_{DD} Section						
V_{DD-OP}	Continuous Operation Voltage				22	V
V_{DD-ON}	Turn-on Threshold Voltage		15.5	16.5	17.5	V
V_{DD-OFF}	Turn-off Threshold Voltage		10.5	11.5	12.5	V
I_{DD-ST}	Start-up Current	V_{DD}=V_{DD-ON} − 0.1V		9	15	µA
I_{DD-OP}	Operating Supply Current	V_{DD}=15V, GATE with 1nF to GND		3.0	3.5	mA
V_{DD-OVP}	V_{DD} Over-voltage Protection level	Auto Restart	24	25	26	V
$t_{D-VDDOVP}$	V_{DD} Over-voltage Protection Debounce	Auto Restart		100		µs
Feedback Input Section						
$V_{FB-OPEN}$	FB Output High Voltage		5			V
V_{FB-OL}	FB Open-loop Trigger Level		4.3	4.6	4.9	V
t_{D-OLP}	Delay Time of FB Pin Open-loop Protection			56		ms
V_{FB-N}	Green-Mode Entry FB Voltage		2.60	2.85	3.10	V
V_{FB-G}	Green-Mode Ending FB Voltage			2.2		V
S_G	Green-Mode Modulation Slope	R_I=95KΩ	40	75	100	Hz/mV
Current-Sense Section						
Z_{SENSE}	Input Impedance		10			KΩ
t_{PD}	Delay to Output	V_{DD}=13.5 to 22V	40	55	100	ns
V_{STHFL}	Flat Threshold Voltage for Current Limit			1		V
V_{STHVA}	Valley Threshold Voltage for Current Limit		0.75	0.80	0.85	V
t_{LEB}	Leading-Edge Blanking Time		250	310	370	ns
DCY_{SAW}	Duty Cycle of SAW Limit	Maximum Duty Cycle		45		%
Oscillator Section						
F_{OSC}	Center Frequency	R_I=95KΩ	65	70	75	KHz
	Hopping Range			±4.9		
t_{HOP}	Hopping Period	R_I=95KΩ		3.7		ms
F_{OSC-G}	Green-Mode Frequency	R_I=95KΩ		20		KHz
F_{DV}	Frequency Variation vs. V_{DD} Deviation	V_{DD}=13.5 to 22V	0	0.02	2.00	%
F_{DT}	Frequency Variation vs. Temperature Deviation	T_A=-20 to 85°C			2	%
Output Section						
DCY_{MAX}	Maximum Duty Cycle		70	75	80	%
V_{GATE-L}	Output Voltage Low	V_{DD}=15V, I_O=20mA			1.5	V
V_{GATE-H}	Output Voltage High	V_{DD}=13.5V, I_O=20mA	8			V
t_r	Rising Time	V_{DD}=15V, C_L=1nF		200		ns
t_f	Falling Time	V_{DD}=15V, C_L=1nF		55		ns
$V_{GATE-CLAMP}$	Output Clamp Voltage	V_{DD}=22V	16	17	18	V

Functional Description

SG5851 devices integrate many useful designs into one controller for low-power switch-mode power supplies. The following descriptions highlight some of the features of the SG5851 series.

Start-up Current

The start-up current is only 9µA, which allows a start-up resistor with a high resistance and a low-wattage to supply the start-up power for the controller. A 1.5MΩ, 0.25W, start-up resistor and a 10µF/25V V_{DD} hold-up capacitor are sufficient for an AC-to-DC power adapter with a wide input range (90V_{AC} to 264V_{AC}).

Operating Current

The operating current has been reduced to 3mA, which results in higher efficiency and reduces the V_{DD} hold-up capacitance requirement.

Green-Mode Operation

The proprietary green-mode function provides off-time modulation to linearly decrease the switching frequency under light-load conditions. On-time is limited to provide stronger protection against brownouts and abnormal conditions. The feedback current, which is sampled from the voltage feedback loop, is taken as the reference. Once the feedback current exceeds the threshold current, the switching frequency starts to decrease. This green-mode function dramatically reduces power consumption under light-load and zero-load conditions. Power supplies using the SG5851 can meet even the strictest regulations regarding standby power consumption.

Oscillator Operation

A resistor connected from the RI pin to ground generates a constant current source used to charge an internal capacitor. The charge time determines the internal clock speed and the switching frequency. Increasing the resistance reduces the amplitude of the input current and reduces the switching frequency. A 95kΩ resistor, R_I, results in a 50µA constant current, I_I, and a 70kHz switching frequency. The relationship between R_I and the switching frequency is:

$$f_{PWM} = \frac{6650}{R_I(k\Omega)} (kHz) \qquad (1)$$

The range of the oscillation frequency is designed to be within 50kHz ~ 100kHz.

Leading-Edge Blanking

Each time the power MOSFET is switched on, a turn-on spike occurs at the sense-resistor. To avoid premature termination of the switching pulse, a 320ns leading-edge blanking time is built in. Conventional RC filtering can therefore be omitted. During this blanking period, the current-limit comparator is disabled and it cannot switch off the gate driver.

Constant Output Power Limit

When the SENSE voltage across the sense resistor, R_S, reaches the threshold voltage (~1.00V), the output GATE drive is turned off after propagation delay, t_{PD}. This propagation delay introduces an additional current proportional to $t_{PD} \cdot V_{in}/L_p$. The propagation delay is nearly constant regardless of the input line voltage V_{IN}. Higher input line voltages result in larger additional currents. At high input line voltages, the output power limit is higher than at low input line voltages.

To compensate for this output power limit variation across a wide AC input range, the threshold voltage is adjusted by adding a positive ramp. This ramp signal rises from 0.80V to 1.00V, then flattens out at 1.00V. A smaller threshold voltage forces the output GATE drive to terminate earlier. This reduces the total PWM turn-on time and makes the output power equal to that of low line input. This proprietary internal compensation ensures a constant output power limit for a wide AC input voltage range (90V_{AC} to 264V_{AC}).

Under-Voltage Lockout (UVLO)

The turn-on and turn-off thresholds are fixed internally at 16.5V and 11.5V. During start-up, the hold-up capacitor must be charged to 16.5V through the start-up resistor to enable SG5851. The hold-up capacitor continues to supply V_{DD} until power can be delivered from the auxiliary winding of the main transformer. V_{DD} must not drop below 11.5V during the start-up process. This UVLO hysteresis window ensures that the hold-up capacitor is adequate to supply V_{DD} during start-up.

Gate Output

The SG5851 BiCMOS output stage is a fast totem-pole gate driver. Cross conduction has been avoided to minimize heat dissipation, increase efficiency, and enhance reliability. The output driver is clamped by an internal 17V Zener diode to protect power MOSFET transistors against undesired over-voltage gate signals.

Built-in Slope Compensation

The sensed voltage across the current sense resistor is used for current mode control and pulse-by-pulse current limiting. Built-in slope compensation improves stability and prevents sub-harmonic oscillations due to peak-current mode control. The SG5851 has a synchronized, positively-sloped ramp built-in at each switching cycle. The slope of the ramp is:

$$\frac{0.36 \times Duty}{Duty(max.)} \qquad (2)$$

Noise Immunity

Noise from the current sense or the control signal can cause significant pulse-width jitter, particularly in continuous-conduction mode. While slope compensation helps alleviate these problems, further precautions should be taken. Good placement and layout practices should be followed. Avoiding long PCB traces and component leads, locating compensation and filter components near the SG5851, and increasing power MOS gate resistance improve performance.

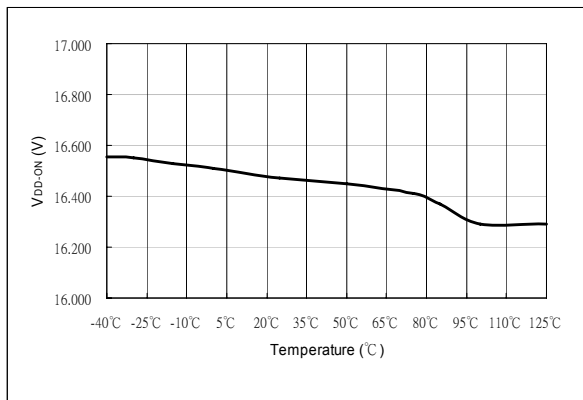## Typical Performance Characteristics

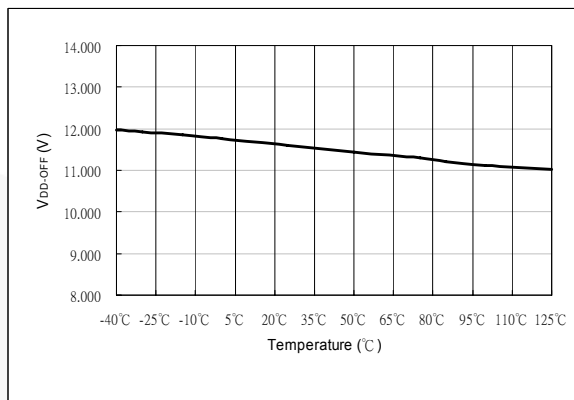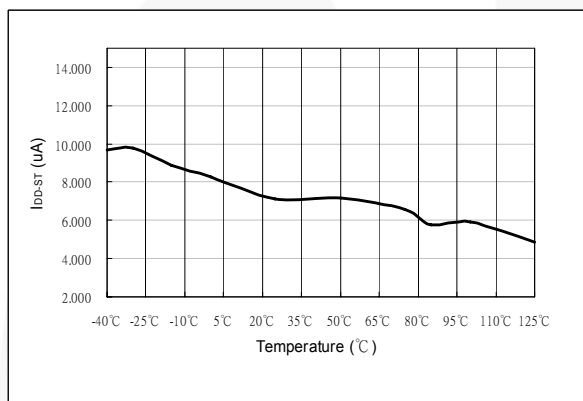**Figure 4.** V_{DD-ON} **vs. T**_A

Figure 5. V_{DD-OFF} **vs. T**_A

Figure 6. I_{DD-ST} **vs. T**_A

Figure 7. I_{DD-OP} **vs. T**_A
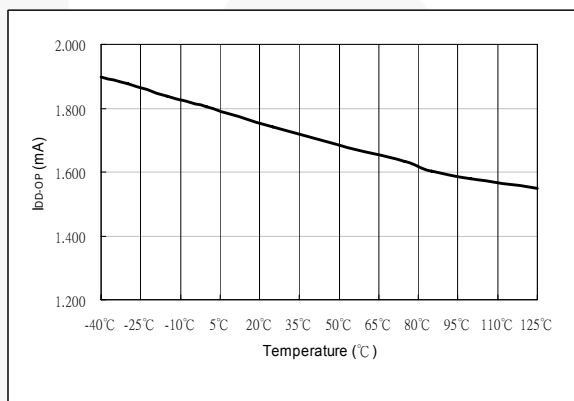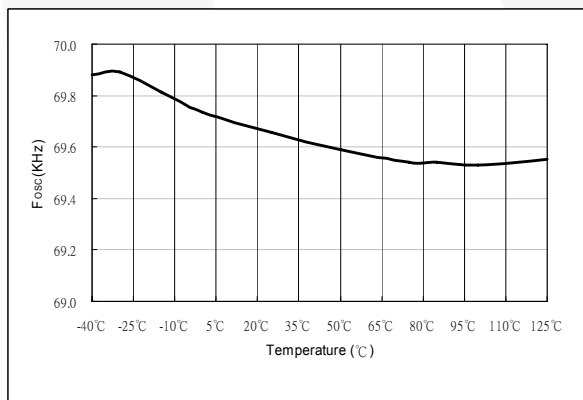

Figure 8. f_{OSC} **vs. T**_A
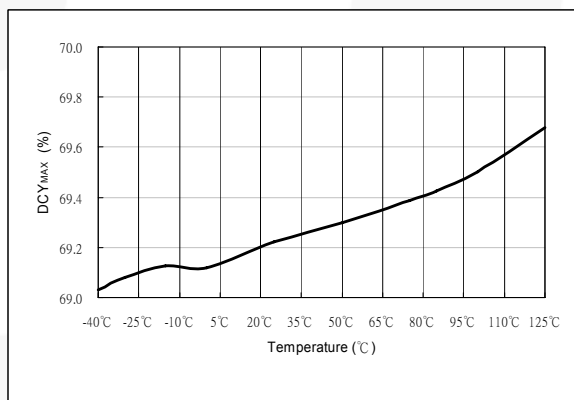
Figure 9. DCY_{MAX} **vs. T**_A
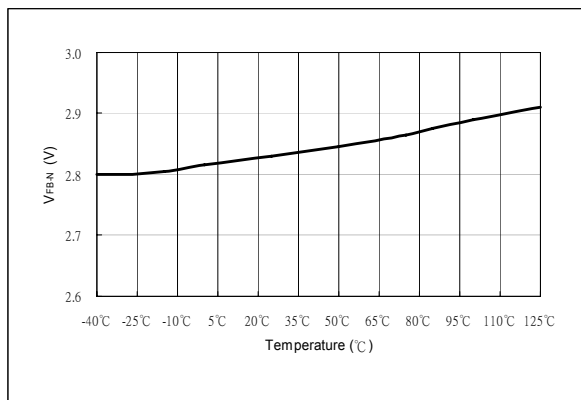
Typical Performance Characteristics
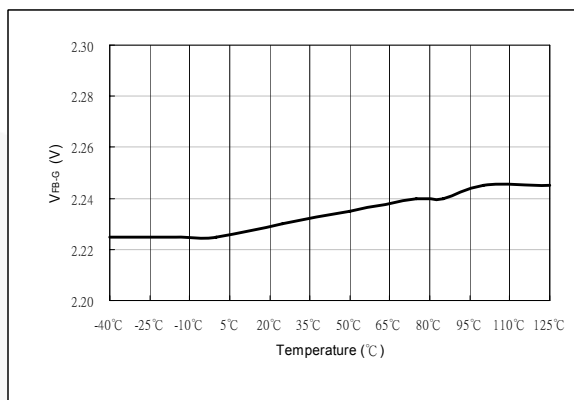
Figure 10. V_{FB-N} vs. T_A

Figure 11. V_{FB-G} vs. T_A
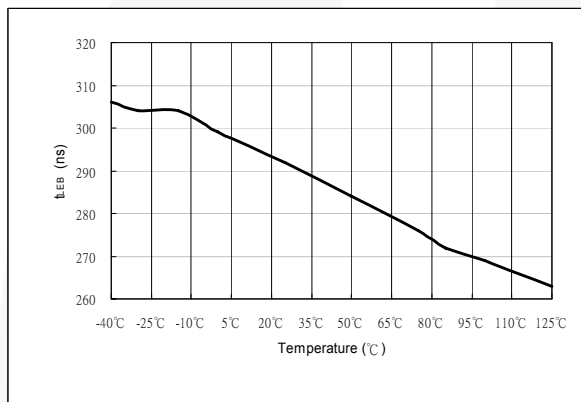
Figure 12. t_{LEB} vs. T_A

Mechanical Dimensions
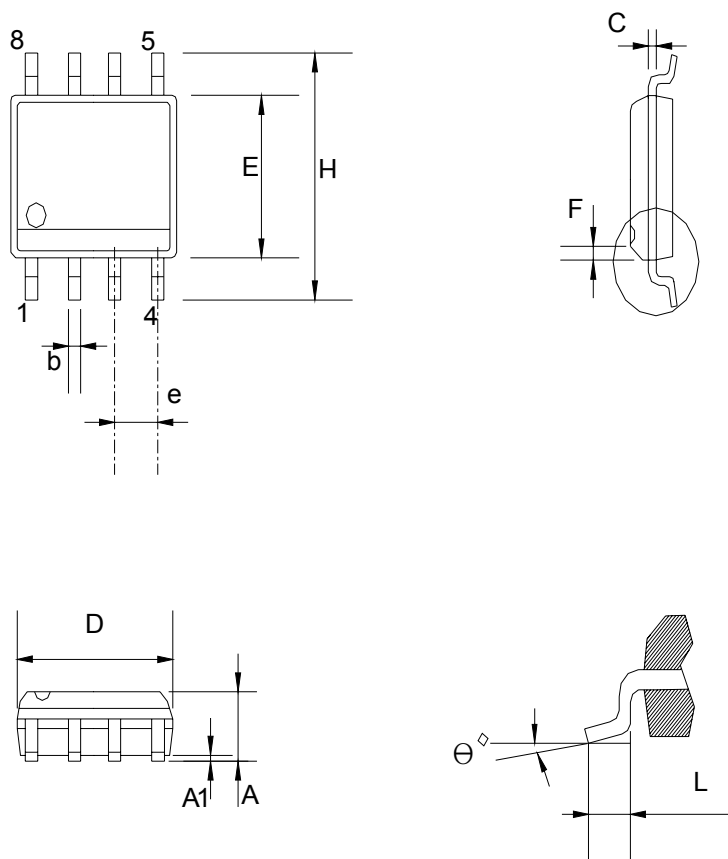
Figure 13.   8-SOIC

Dimensions

Symbol	Millimeter			Inch		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	1.346		1.752	0.053		0.069
A1	0.101		0.254	0.004		0.010
b		0.406			0.016	
c		0.203			0.008	
D	4.648		4.978	0.183		0.196
E	3.810		3.987	0.150		0.157
e		1.270			0.050	
F		0.381X45˚			0.015X45˚	
H	5.791		6.197	0.228		0.244
L	0.406		1.270	0.016		0.050
θ˚	0˚		8˚	0˚		8˚

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Mechanical Dimensions (Continued)
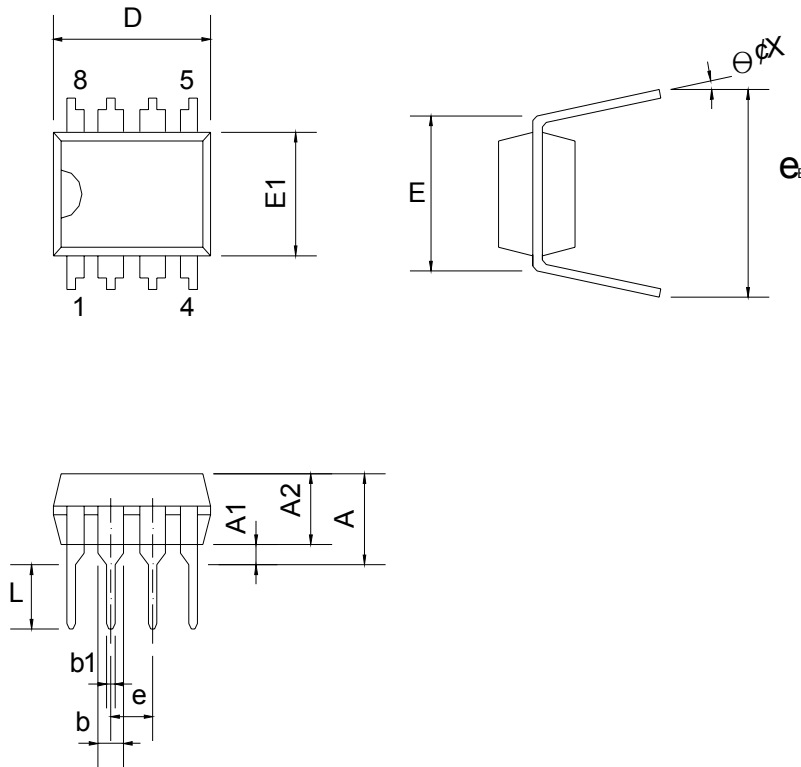
Figure 14.   8-DIPIC

Dimensions

Symbol	Millimeter			Inch		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A			5.334			0.210
A1	0.381			0.015		
A2	3.175	3.302	3.429	0.125	0.130	0.135
b		1.524			0.060	
b1		0.457			0.018	
D	9.017	9.271	10.160	0.355	0.365	0.400
E		7.620			0.300	
E1	6.223	6.350	6.477	0.245	0.250	0.255
e		2.540			0.100	
L	2.921	3.302	3.810	0.115	0.130	0.150
e$_B$	8.509	9.017	9.525	0.335	0.355	0.375
θ°	0°	7°	15°	0°	7°	15°

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